# METHOD OF MAKING WIRE CONNECTIONS OF PREDETERMINED SHAPE


## ABSTRACT

In a method of making a wire connection (1) of predetermined shape between a first connecting point (2) located on a semiconductor chip (3) and a second connecting point (4), a capillary is moved along a predetermined trajectory (6). After attaching the wire (7) at the first connecting point (2), the capillary is moved up to a first point ($P_1$; $P_1'$) for the preforming of one or two kinks ($K_2$; $K_1$, $K_2$) and for the pulling out of the wire (7) as far as the required total length (L) of the wire connection (1). From the first point ($P_1$; $P_1'$), the capillary is moved along a circular arc (10) up to a second point ($P_2$; $P_2'$), at which the wire (7) is locked in the capillary. The circular arc (10) is centred in the first connecting point (2) or in the immediate vicinity of the first connecting point (4).

The method is suitable for the wiring of CSPs (Chip Scale Package). The movement along the circular arc (10) prevents the wire from being pushed back through the capillary. As soon as the wire is locked in the capillary, the second connecting point (4) can be approached without difficulty.

(Fig. 2)